PRELIMINARY

SOLID STATE DEVICES, INC

SFF140-28

14849 Firestone Boulevard · La Mirada,CA 90638
Phone: (714) 670-SSDI (7734) · Fax: (714) 522-7424

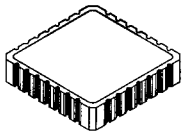
Designer's Data Sheet

28*AMP
100 VOLT
0.095 Ω
N-CHANNEL
POWER MOSFET

FEATURES:

- Rugged construction with poly silicon gate
- Low RDS(on) and high transconductance
- Excellent high temperature stability
- Very fast switching speed
- Fast recovery and superior dv/dt performance
- Increased reverse energy capability
- Low input and transfer capacitance for easy paralleling
- Hermetically sealed surface mount package
- TX, TXV and Space Level screening available
- Replaces: IRF140 Types

28 PIN CLCC



MAXIMUM RATINGS

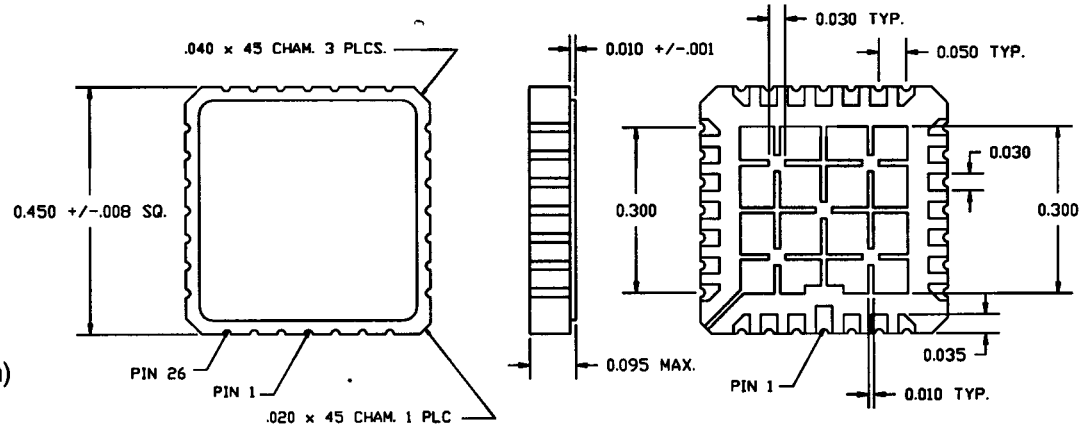
CHARACTERISTIC	SYMBOL	VALUE	UNIT
Drain to Source Voltage	V_{DS}	100	Volts
Gate to Source Voltage	V_{GS}	±20	Volts
Continuous Drain Current	I_D	28*	Amps
Operating and Storage Temperature	T_{op} & T_{stg}	-55 to +150	°C
Thermal Resistance, Junction to Case	$R_{\theta JC}$	3.5	°C/W
Total Device Dissipation @ TC=25°C Total Device Dissipation @ TC=80°C	P_D	20* 20	Watts

PACKAGE OUTLINE: 28 PIN CLCC

PIN OUT:
SOURCE: 1, 15-28
DRAIN: 5-11
GATE: 2, 3, 13, 14

NOTE:

All Drain/Source Pins must be connected on the PC Board in order to maximize current capability and minimize RDS(on)



*** Rating based on size of chip. Device rating may vary depending on mounting and heatsink conditions. Consult SSDI Marketing department for thermal derating details.**

NOTE: All specifications are subject to change without notification. SCD's for these devices should be reviewed by SSDI prior to release.	DATA SHEET #: F00003 B	MED

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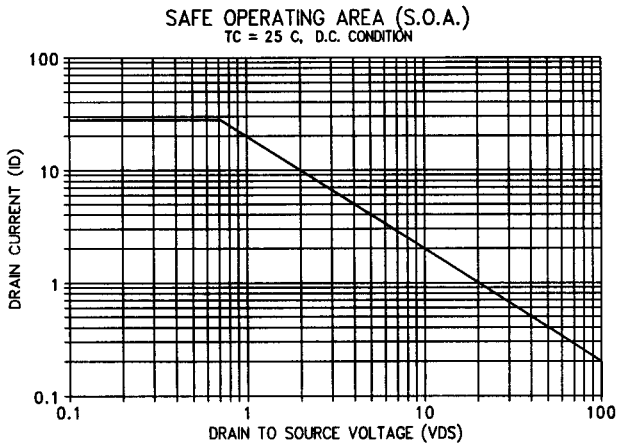
ELECTRICAL CHARACTERISTICS @ T_J=25°C (Unless Otherwise Specified)

RATING		SYMBOL	MIN	TYP	MAX	UNIT
Drain to Source Breakdown Voltage (VGS=0 V, ID=250µA)		BV_{DSS}	100	---	---	V
Drain to Source on State Resistance (VGS=10 V, ID=60% Rated ID		$R_{DS(on)}$	---	0.075	0.095**	Ω
On State Drain Current (VDS >ID(on) X RDS(on) Max, VGS=10 V		$I_{D(on)}$	28*	---	---	A
Gate Threshold Voltage (VDS=VGS, ID=250µA)		$V_{GS(th)}$	2.0	---	4.0	V
Forward Transconductance (VDS >ID(on) X RDS(on) Max, IDS=60% rated ID)		g_{fs}	8.7	11	---	S(℧)
Zero Gate Voltage Drain Current (VDS=max rated voltage, VGS=0 V) (VDS=80% rated VDS, VGS=0 V, TA=150°C)		I_{DSS}	--- ---	--- ---	250 1000	µA
Gate to Source Leakage Forward **Gate to Source Leakage Reverse**	At rated VGS	I_{GSS}	--- ---	--- ---	100 -100	nA
Total Gate Charge **Gate to Source Charge** **Gate to Drain Charge**	VGS=10 Volts 50% rated VDS Rated ID	Q_g Q_{gs} Q_{gd}	--- --- ---	40 8 20	59 12 28	nC
Turn on Delay Time **Rise Time** **Turn Off Delay Time** **Fall Time**	VDD=50% rated VDS rated ID RG= 9.1Ω	$t_{d(on)}$ t_r $t_{d(off)}$ t_f	--- --- --- ---	15 72 40 50	23 110 60 75	nsec
Diode Forward Voltage (IS=rated ID, VGS=0 V, TJ=25°C)		V_{SD}	---	---	2.5	V
Diode Reverse Recovery Time **Reverse Recovery Charge**	TJ=25°C IF=10A di/dt=100 A/µsec	t_{rr} Q_{RR}	70 0.44	150 0.91	300 1.9	nsec µC
Input Capacitance **Output Capacitance** **Reverse Transfer Capacitance**	VGS=0 Volts VDS=25 Volts f= 1 MHz	Ciss Coss Crss	--- --- ---	1500 500 90	--- --- ---	pF



NOTES:

* Rating based on size of chip. Device rating may vary depending on mounting and heatsink conditions. Consult SSDI Marketing department for thermal derating details.

** Due to package resistance; all Source/Drain pins must be connected on the PC Board in order to obtain the lowest RDS(on) possible.